

Qualification Description:

The information contained herein represents proof of Reliability and Performance of the Package Series listed below in accordance with the Qualification Plan and test methods referenced in Section 7.0, after exposure to a variety of environments and mechanical events that occur during installation and operational lifetime of the product. Upon conclusion of the testing the product continued to operate within specification limits, demonstrating its capability of reliable operation throughout its lifetime.

The purpose of this report is to present Qualification Test results of the referenced Package Series. The Pericom product data presented in this report qualifies the products manufactured in this package configuration, using the same bill of materials and assembled by the identified subcontractor location. The report describes the qualification test program, procedures utilized, criteria enforced (at the time of product validation), and specific result data obtained during the testing of three lots of semiconductors. The three lots consist of an equal number of units from different date codes, from the same production line and SubContractor to ensure manufacturing repeatability.

Lot Background Information:

Qual Vehicle:	PI3HDMI301FFE
Supplier (Code):	GTK (G)
Pkg Type - Code:	LQFP-80 (FF80)
Outline Drawing:	PD2064
By Extension Pkg:	FB64 FB48 FB32 FC64

Qual Test Date:	Feb-2011 updated Nov-2013
Die Attach Material:	1076DJ-G
Wire Size & Material:	0.8mil PdCu
Mold Compound:	G631M
Leadframe Material:	C7025
Lead Finish:	100% Matte Sn

Pericom's Qualification Test Results:

Stress Test	Test Procedure	Test Conditions	Duration	# of Lots	Samples per Lot	Results Pass/Fail
Preconditioning	JESD22-A113	MSL3	NA	3	154	462 / 0
CSAM	J-STD-020	No delamination of Die Top, Wire bond, Down bond areas	NA	3	22	66 / 0
PreCon UHAST	JESD22-A118	130°C, RH 85%, 33.3 psia, 0V	96 hrs	3	77	231 / 0
PreCon BHAST (QBE: LQFP128 PN=PI7C9X440SLBFDE)	JESD22-A110	130°C, RH 85%, 33.3 psia, 1.2V	96 hrs	3	77	231 / 0
		130°C, RH 85%, 33.3 psia, 1.2V	192 hrs	3	77	231 / 0
PreCon Temp Cycle	JESD22-A104	-65°C to +150°C 500 Cycles	100 cycles	3	77	231 / 0
		-65°C to +150°C 500 Cycles	500 cycles	3	77	231 / 0
HTSL (no PreCon)	JESD22-A103	1000hrs, 0V, 150°C	500 hrs	3	77	231 / 0
		1000hrs, 0V, 150°C	1000 hrs	3	77	231 / 0
Physical Dimension	JESD22-B100	NA	NA	3	5	15 / 0
External Visual Insp	JESD22-B101	NA	NA	3	5	15 / 0
Solderability	J-STD-020	Pb-Free Solder Dip 245°C	NA	3	3	9 / 0

Qualification by Extension Information:

Where a product of interest is not sampled during this period, it is valid to use the reliability data of the particular process technology or package type family to which the part belongs. All parts within the same family are designed to the same rules, and manufacturing is controlled by SPC. Within a product family, a device can only be fabricated on one process technology/ option, and only assembled on one package type process.

If there are any questions about this qualification, please contact Quality Support at:

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Date:	Feb-2011 updated Nov-2013
PKG Type & Code:	LQFP-80 (FF80) QBE: FB64 FB48 FB32 FC64
Assembler-Code:	GTK (G)
Qual Vehicle:	PI3HDMI301FFE

By extension: Pericom active devices using the Fab/Process at the time of the Qualification:

PI3HDMI2310FFE				
PI3HDMI2310FFEX				
PI3HDMI2410-AFFE				
PI3HDMI2410-AFFEX				
PI3HDMI2410FFE				
PI3HDMI2410FFEX				
PI3HDMI301FFE				
PI3HDMI301FFEX				
PI3HDMI341ARCFE				
PI3HDMI341ARCFFEX				
PI3HDMI341ARTFFE				
PI3HDMI341ARTFFEX				
PI3HDMI336FBE				
PI3HDMI336FBEX				
PI3HDMI621FBE				
PI3HDMI621FBEX				
PI6C487016FBE				
PI6C487016FBEX				
PI6C2952FBE				
PI6C2952FBEX				
PI6C484321FBE				
PI6C484321FBEX				
PI90SD1636AFCE				
PI90SD1636AFCEX				
PI90SD1636CFCE				
PI90SD1636CFCEX				
PI90SD1636DFCE				
PI90SD1636DFCEX				

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